Single 2-Input AND Gate

The NL17SV08 is an ultra-high performance 2-Input AND gate manufactured in 0.35µ CMOS technology with excellent performance down to 0.9 volts. This device is ideal for extremely high-speed and high-drive applications. Additionally, limitations of board space are no longer a constraint. The very small SOT-553 makes this device fit most tight designs and spaces.

Features

- Extremely High Speed: $t_{PD} = 1.0 \text{ ns} (Typ) @ V_{CC} = 3.3 \text{ V}$
- Designed for 0.9 to 3.3 V Operation
- Overvoltage Tolerance (OVT)* Input Pins Permit Logic Translation
- Balanced ± 24 mA Output Drive @ 3.3 Volts
- Near Zero Static Supply Current
- Ultra-Tiny SOT-553 5 Pin Package Only 1.6 x 1.6 x 0.6 mm
- All Devices in Package SOT-553 are Inherently Pb-Free**

Typical Applications

- Cellular
- Digital Camera
- PDA
- Digital Video

Industry Standard

• Functionally Similar to NC7SV08 and SN74AUC1G08

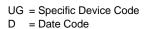


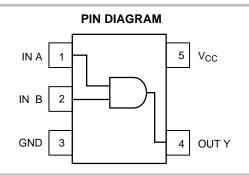
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PIN ASSIGNMENT

PIN #	FUNCTION
1	IN A
2	IN B
3	GND
4	OUT Y
5	V _{CC}

FUNCTION TABLE

Input A	Input B	Output Y
L	L	L
L	Н	L
Н	L	L
Н	Н	Н

*Overvoltage Tolerance (OVT) enables input pins to function outside (higher) of their operating voltages, with no damage to the devices or to signal integrity.

ORDERING INFORMATION

**For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

MAXIMUM RATINGS

Symbol	Rating		Value	Unit
V _{CC}	DC Supply Voltage		-0.5 to + 4.6	V
VI	DC Input Voltage		-0.5 to + 4.6	V
Vo	DC Output Voltage		–0.5 to V _{CC} +0.5	V
Ι _{ΙΚ}	DC Input Diode Current	V _I < GND	±50	mA
Ι _{ΟΚ}		V _O = GND V _O = V _{CC}	-50 +50	mA
Ι _Ο	DC Output Sink Current		±50	mA
I _{CC}	DC Supply Current per Supply Pin		±50	mA
I _{GND}	DC Ground Current per Ground Pin		±50	mA
T _{STG}	Storage Temperature Range		- 65 to +150	°C
ΤL	Lead Temperature, 1.0 mm from Case for 10 seconds		260	°C
ТJ	Junction Temperature Under Bias		+150	°C
θ_{JA}	Thermal Resistance (Note 1)		250	°C/W
PD	Power Dissipation in Still Air at 85°C		250	mW
MSL	Moisture Sensitivity		Level 1	
F _R	Flammability Rating Oxygen Index	: 28 to 34	UL 94 V–0 @ 0.125 in	

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.
Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2 ounce copper trace no air flow.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Max	Unit
V _{CC}	Positive DC Supply Voltage	0.9	3.6	V	
V _{IN}	Digital Input Voltage		0	3.6	V
V _{out}	Output Voltage	0	V _{CC}	V	
I _{OH} /I _{OL}				± 24 ± 18 ± 6 ± 4 ± 2 ± 0.1	mA
t _A	Operating Temperature Range. All Package Types		-40	+85	°C
t _r , t _f	Input Rise or Fall Time	$V_{\rm CC} = 3.3 \text{V} \pm 0.3 \text{ V}$	0	10	nS/V

DEVICE JUNCTION TEMPERATURE VERSUS TIME TO 0.1% BOND FAILURES

Junction Temperature °C	Time, Hours	Time, Years
80	1,032,200	117.8
90	419,300	47.9
100	178,700	20.4
110	79,600	9.4
120	37,000	4.2
130	17,800	2.0
140	8,900	1.0

DC CHARACTERISTICS- Digital Section (Voltages Referenced to GND)

				T _A =	25°C	T _A = −40 to 85°C		
Symbol	Parameter	Condition	V _{CC}	Min	Мах	Min	Max	Unit
VIH	High Level		0.90	0.65 x V _{CC}		0.65 x V _{CC}		V
	Input Voltage		$1.10 \le = V_{CC} \le 1.30$	0.65 x V _{CC}		0.65 x V _{CC}		
			$1.40 \le V_{CC} \le 1.60$	$0.65 \times V_{CC}$		$0.65 \times V_{CC}$		
			$1.65 \le V_{CC} \le 1.95$	$0.65 \times V_{CC}$		$0.65 \times V_{CC}$		
			$2.30 \le V_{CC} \le 2.70$	1.6		1.6		
			$2.70 \le V_{CC} \le 3.60$	2.0		2.0		
VIL	Low Level		0.90		$0.35 \times V_{CC}$		$0.35 \times V_{CC}$	V
	Input Voltage		$1.10 \le V_{CC} \le 1.30$		0.35 x V _{CC}		0.35 x V _{CC}	
			$1.40 \le V_{CC} \le 1.60$		0.35 x V _{CC}		0.35 x V _{CC}	
			$1.65 \le V_{CC} \le 1.95$ $2.30 \le V_{CC} \le 2.70$		0.35 x V _{CC} 0.7		0.35 x V _{CC} 0.7	
			$2.30 \le V_{CC} \le 2.70$ $2.70 \le V_{CC} \le 3.60$		0.7		0.7	
V _{OH}	High Level	I _{OH} = –100 μA	0.90	V _{CC} – 0.1		V _{CC} – 0.1		V
чон	Output Voltage	10H = 100 µ/	$1.10 \le V_{CC} \le 1.30$	V _{CC} – 0.1		V _{CC} – 0.1		•
			$1.40 \le V_{CC} \le 1.60$	$V_{CC} - 0.2$		$V_{CC} - 0.2$		
			$1.65 \le V_{CC} \le 1.95$	V _{CC} – 0.2		V _{CC} – 0.2		
			$2.30\leqV_{CC}\leq2.70$	V _{CC} – 0.2		V _{CC} – 0.2		
			$2.70 \le V_{CC} \le 3.60$	V _{CC} – 0.2		V _{CC} – 0.2		
		I _{OH} = -2.0 mA	$1.10 \le V_{CC} \le 1.30$	$0.75 \times V_{CC}$		0.75 x V _{CC}		
		I _{OH} = -4.0 mA	$1.40 \le V_{CC} \le 1.60$	0.75 x V _{CC}		0.75 x V _{CC}		
	I _{OH} = -6.0 mA	$1.65 \le V_{CC} \le 1.95$	1.25		1.25			
			$2.30 \le V_{CC} \le 2.70$	2.0		2.0		
		I _{OH} = -12 mA	$2.30 \le V_{CC} \le 2.70$	1.8		1.8		
			$2.70 \le V_{CC} \le 3.60$	2.2		2.2		
		I _{OH} = –18 mA	$2.30 \le V_{CC} \le 2.70$ $2.70 \le V_{CC} \le 3.60$	1.7 2.4		1.7 2.4		
		I _{OH} = -24 mA	$2.70 \le V_{CC} \le 3.60$ $2.70 \le V_{CC} \le 3.60$	2.4		2.4		
Max	Low Level	$I_{OL} = 100 \mu A$	0.90	2.2	0.1	2.2	0.1	V
V _{OL}	Output Voltage	ΙΟΓ = 100 μΑ	$1.10 \le V_{CC} \le 1.30$		0.1 0.1		0.1 0.1	v
			$1.40 \le V_{CC} \le 1.60$		0.2		0.2	
			$1.65 \le V_{CC} \le 1.95$		0.2		0.2	
			$2.30 \le V_{CC} \le 2.70$		0.2		0.2	
			$2.70 \le V_{CC} \le 3.60$		0.2		0.2	
		I _{OL} = 2.0 mA	$1.10 \le V_{CC} \le 1.30$		$0.25 \times V_{CC}$		$0.25 \times V_{CC}$	
		I _{OL} = 4.0 mA	$1.40 \le V_{CC} \le 1.60$		$0.25 \times V_{CC}$		$0.25 \times V_{CC}$	
		I _{OL} = 6.0 mA	$1.65 \le V_{CC} \le 1.95$		0.3		0.3	
		I _{OL} = 12 mA	$2.30 \le V_{CC} \le 2.70$		0.4		0.4	
			$2.70 \le V_{CC} \le 3.60$		0.4		0.4	
		I _{OL} = 18 mA	$2.30 \le V_{CC} \le 2.70$		0.6		0.6	
			$2.70 \le V_{CC} \le 3.60$		0.4		0.4	
		I _{OL} = 24 mA	$2.70 \le V_{CC} \le 3.60$		0.55		0.55	
I _{IN}	Input Leakage Current	0 = V _I = 3.6 V	0.90 to 3.60		±0.1		±0.9	μA
I _{OFF}	Power Off Leakage Current		0		10		10	μΑ
I _{CC}	Quiescent Supply Current	$V_{I} = V_{CC}$ or GND	0.90 to 3.60		0.9		5	μA

		-40°C			25°C		85	°C	
Symbol	Parameter	Condition	V _{CC}	Min	Тур	Max	Min	Max	Unit
T _{PHL,}	Propagation Delay	C_L = 15 pF, R_L = 1.0 M Ω	0.90		13				nS
T _{PLH}		C_L = 15 pF, R_L = 2.0 k Ω	$\begin{array}{l} 1.10 \leq V_{CC} \leq 1.30 \\ 1.40 \leq V_{CC} \leq 1.60 \end{array}$	3.0 1.0	6.0 3.2	10.0 6.0	1.0 1.0	14.6 7.2	nS
		C_L = 30 pF, R_L = 500 k Ω	$\begin{array}{l} 1.65 \leq V_{CC} \leq 1.95 \\ 2.30 \leq V_{CC} \leq 2.70 \\ 2.70 \leq V_{CC} \leq 3.60 \end{array}$	1.0 0.8 0.7	2.0 1.2 1.0	4.5 2.6 2.3	1.0 0.7 0.6	5.3 3.7 3.0	nS
C _{IN}	Input Capacitance		0		2.0				pF
C _{OUT}	Output Capacitance		0		4.5				pF
C _{PD}	Power Dissipation Capacitance	$V_I = 0 V \text{ or } V_{CC}$ F = 10 MHz	0.90 to 3.60		20				pF

AC CHARACTERISTICS (Input $t_r = t_f = 3.0 \text{ nS}$)

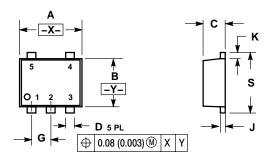
DEVICE ORDERING INFORMATION

Device Order Number	Logic Circuit Indicator	No. of Gates per Package	Temp Range Identifier	Technology	Device Function	Package Suffix	Tape and Reel Suffix	Package Type	Tape and Reel Size [†]
NL17SV08XV5T2	NL	1	7	SV	08	XV5	T2	SOT–553 (Pb–Free)	178 mm 4000 Units

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS

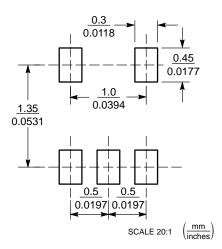
SOT-553 5-LEAD PACKAGE CASE 463B-01 **ISSUE A**



NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: MILLIMETERS 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

	MILLIN	IETERS	INCHES		
DIM	MIN	MAX	MIN MAX		
Α	1.50	1.70	0.059	0.067	
В	1.10	1.30	0.043	0.051	
С	0.50	0.60	0.020	0.024	
D	0.17	0.27	0.007	0.011	
G	0.50	BSC	0.020	BSC	
J	0.08	0.18	0.003	0.007	
K	0.10	0.30	0.004 0.012		
S	1.50	1.70	0.059	0.067	

SOLDERING FOOTPRINT*



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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